

Title (en)
YTTERBIUM SPUTTERING TARGET AND METHOD FOR MANUFACTURING THE TARGET

Title (de)
YTTERBIUM-SPUTTERTARGET UND VERFAHREN ZUR HERSTELLUNG DES TARGETS

Title (fr)
CIBLE DE PULVÉRISATION D'YTTERBIUM ET PROCÉDÉ DE FABRICATION DE LA CIBLE

Publication
EP 2241649 B1 20150121 (EN)

Application
EP 09707362 A 20090205

Priority
• JP 2009051931 W 20090205
• JP 2008028631 A 20080208

Abstract (en)
[origin: US2010044223A1] Provided is a method of producing an ytterbium sputtering target, wherein an ytterbium target material having Vickers hardness (Hv) of the material surface of 15 or more and 40 or less is prepared in advance, and a surface of the ytterbium target material having the foregoing surface hardness is subject to final finish processing by way of machining. With the ytterbium sputtering target, present invention aims to remarkably reduce the irregularities (gouges) on the target surface after the final finish processing of the target material, and to inhibit the generation of particles during sputtering.

IPC 8 full level
C23C 14/34 (2006.01)

CPC (source: EP US)
C22F 1/00 (2013.01 - EP US); **C22F 1/02** (2013.01 - EP US); **C22F 1/16** (2013.01 - EP US); **C23C 14/3414** (2013.01 - EP US)

Citation (examination)
WO 0236847 A2 20020510 - HONEYWELL INT INC [US]

Cited by
US10174402B2; US9945009B2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)
US 2010044223 A1 20100225; US 9328411 B2 20160503; EP 2241649 A1 20101020; EP 2241649 A4 20110202; EP 2241649 B1 20150121; JP 2013177687 A 20130909; JP 5379010 B2 20131225; JP 5744958 B2 20150708; JP WO2009099121 A1 20110526; TW 200936793 A 20090901; TW I525206 B 20160311; WO 2009099121 A1 20090813

DOCDB simple family (application)
US 59449209 A 20090205; EP 09707362 A 20090205; JP 2009051931 W 20090205; JP 2009535162 A 20090205; JP 2013086186 A 20130417; TW 98103816 A 20090206